

Title (en)
MOLD DEVICE FOR FORGING

Title (de)
FORMVORRICHTUNG ZUM SCHMIEDEN

Title (fr)
DISPOSITIF DE TYPE MOULE À DES FINS DE FORGEAGE

Publication
EP 2837440 A4 20160127 (EN)

Application
EP 13769430 A 20130327

Priority
• JP 2012073850 A 20120328
• JP 2013058920 W 20130327

Abstract (en)
[origin: EP2837440A1] A forging die device is provided with an upper die 10 and a lower die 20. At least one die 10 (20) of the upper die 10 and the lower die 20 has a die holder 12 (22) which surrounds the outer periphery of the die 10 (20) and holds the die 10 (20). The die holder 12 (22) is configured to bear the radial tensile stress (tensile force) received by the die 10 (20) during forging. By this means, the die 10 (20) can be miniaturized.

IPC 8 full level
B21J 13/03 (2006.01); **B21J 1/06** (2006.01); **B21J 13/08** (2006.01)

CPC (source: EP US)
B21J 1/06 (2013.01 - EP US); **B21J 13/02** (2013.01 - US); **B21J 13/03** (2013.01 - EP US); **B21J 13/085** (2013.01 - EP);
B21K 29/00 (2013.01 - EP US)

Citation (search report)
• [X] JP H1133663 A 19990209 - HONDA MOTOR CO LTD
• [X] JP H01113145 A 19890501 - KOBE STEEL LTD
• See references of WO 2013146844A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 2837440 A1 20150218; EP 2837440 A4 20160127; EP 2837440 B1 20180926; JP 2013202651 A 20131007; JP 5902978 B2 20160413;
US 2015052962 A1 20150226; US 9682420 B2 20170620; WO 2013146844 A1 20131003

DOCDB simple family (application)
EP 13769430 A 20130327; JP 2012073850 A 20120328; JP 2013058920 W 20130327; US 201314375958 A 20130327